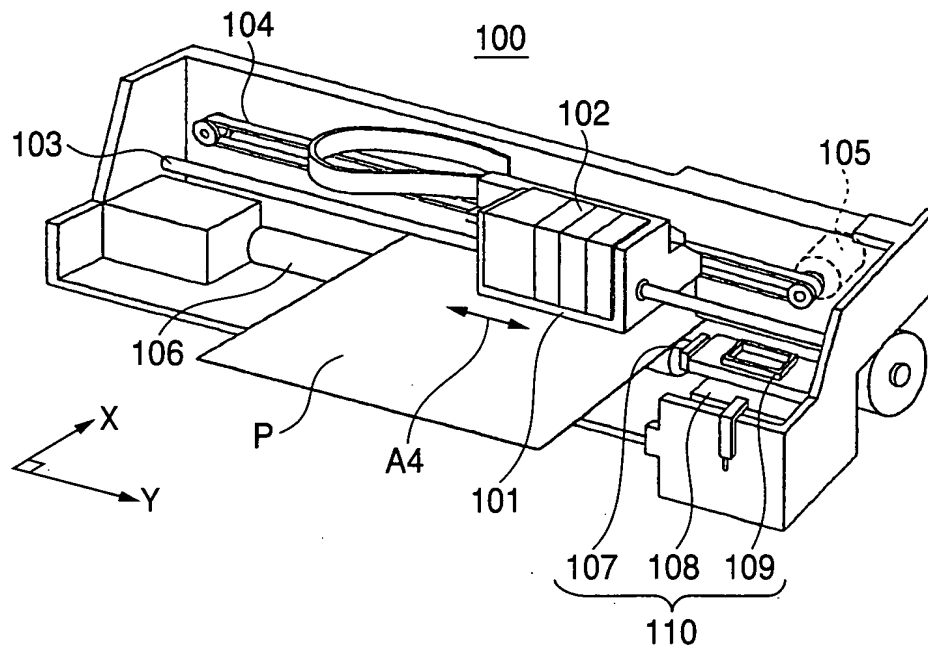




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FIG. 1





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FIG. 2

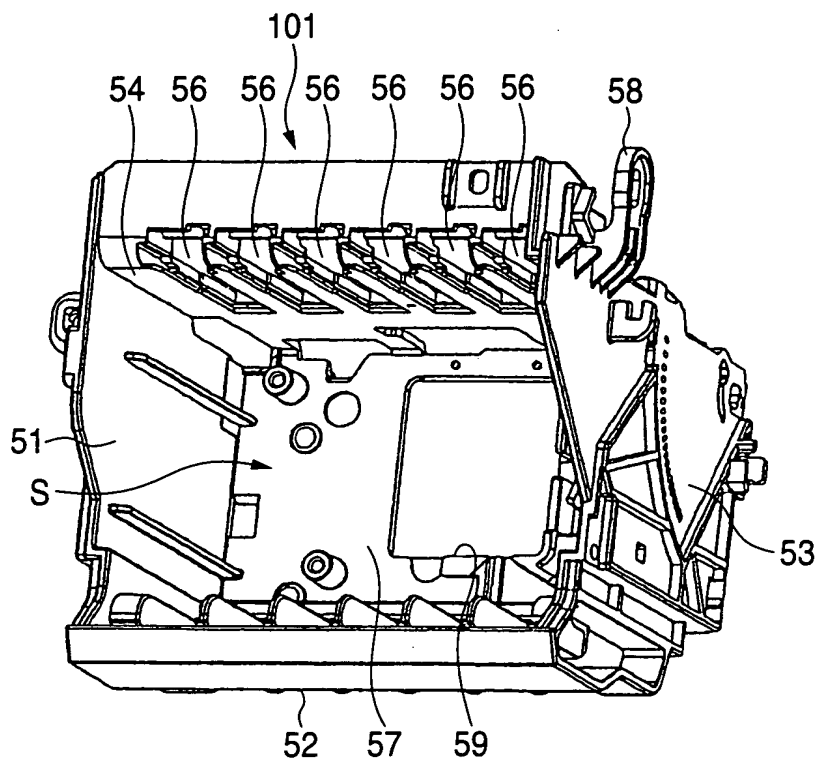
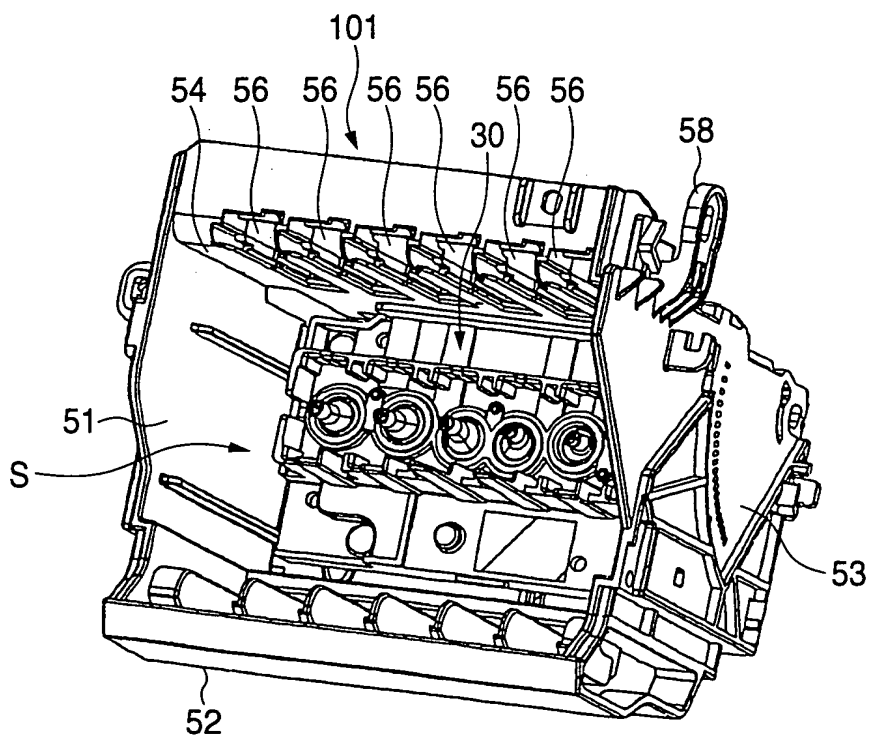
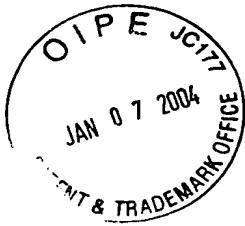


FIG. 3





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FIG. 4

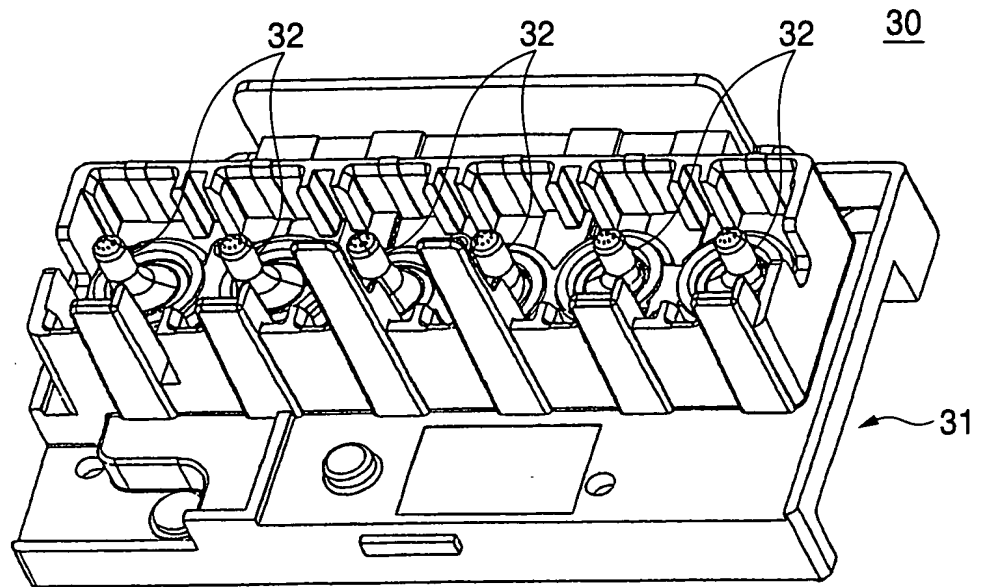
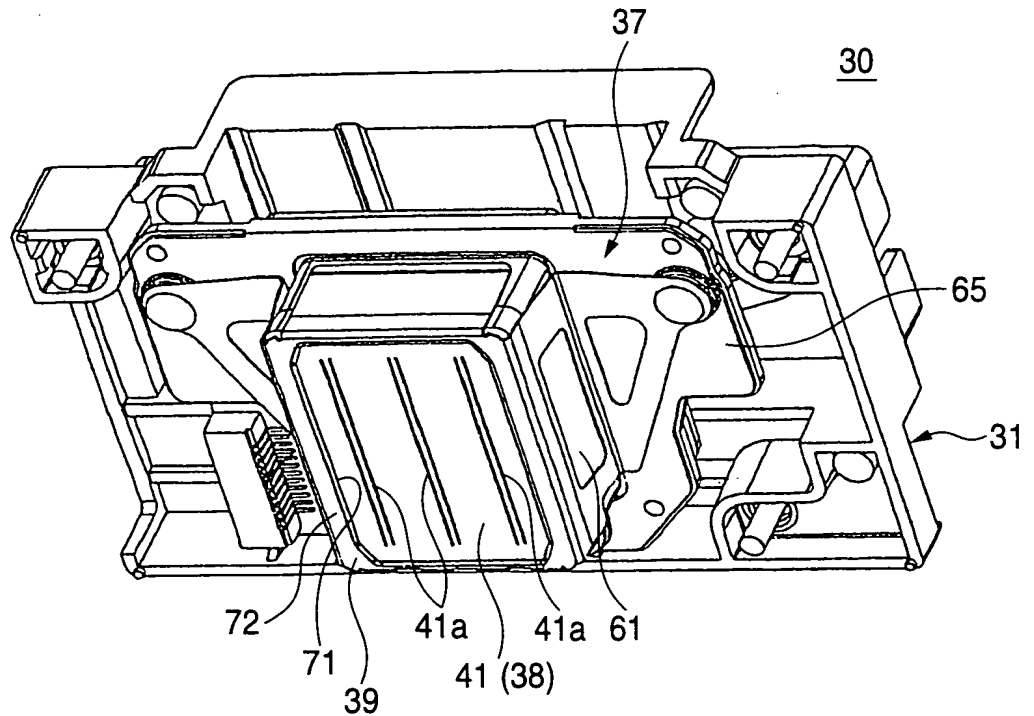


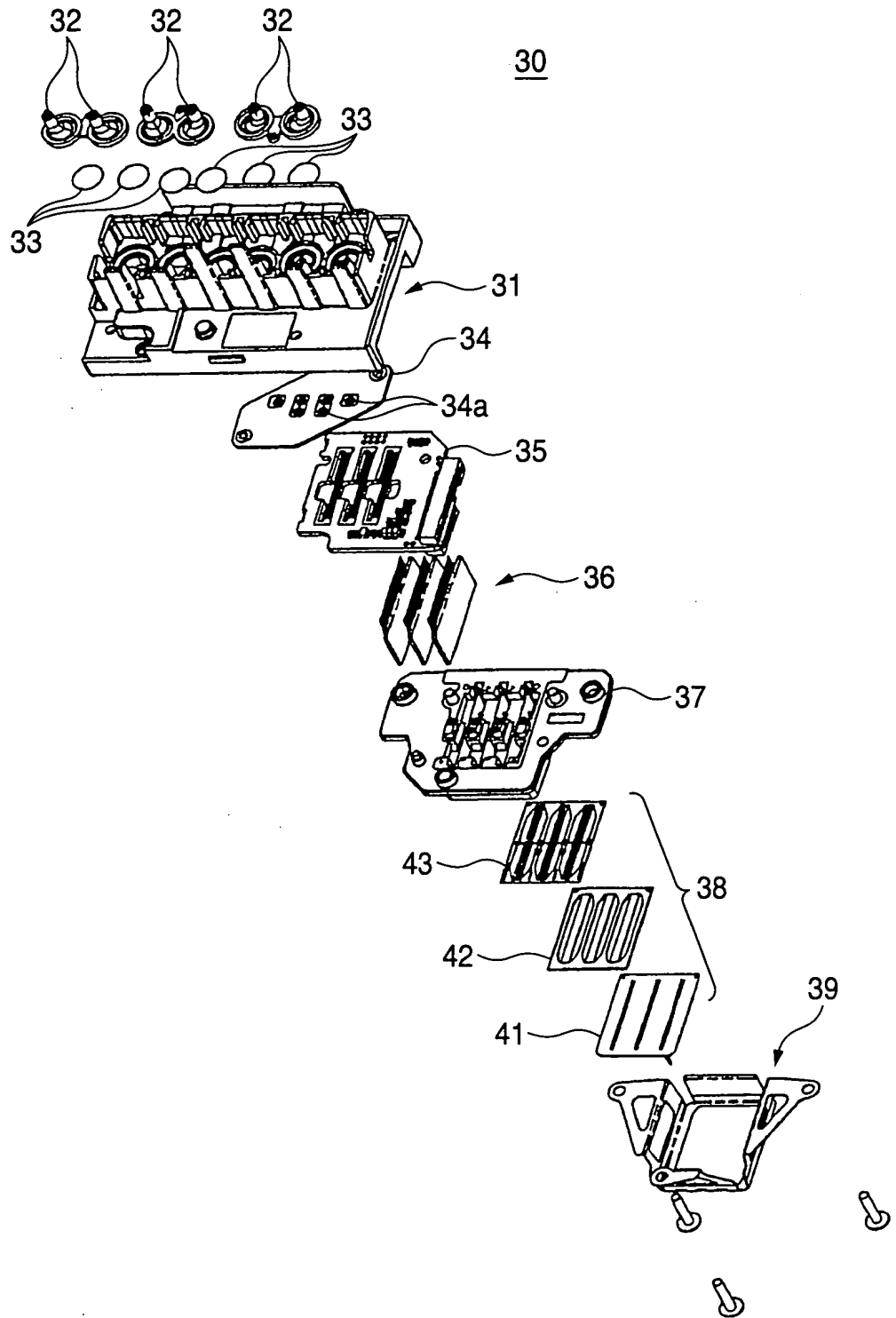
FIG. 5





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FIG. 6





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FIG. 7

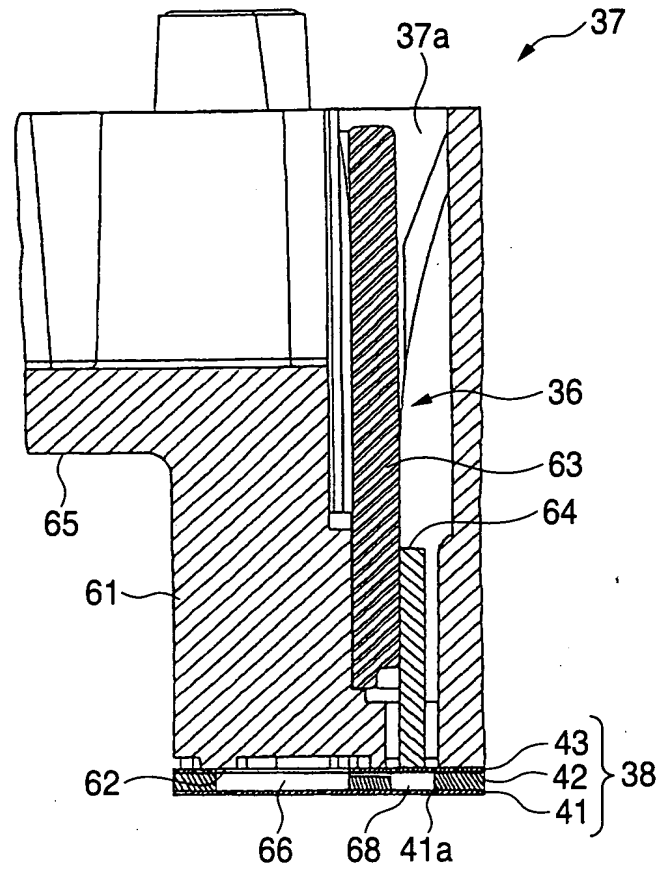
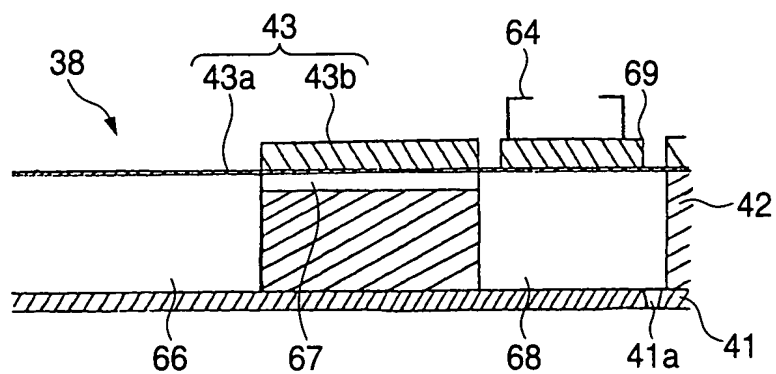


FIG. 8



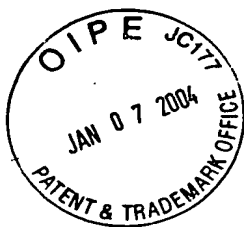


FIG. 9

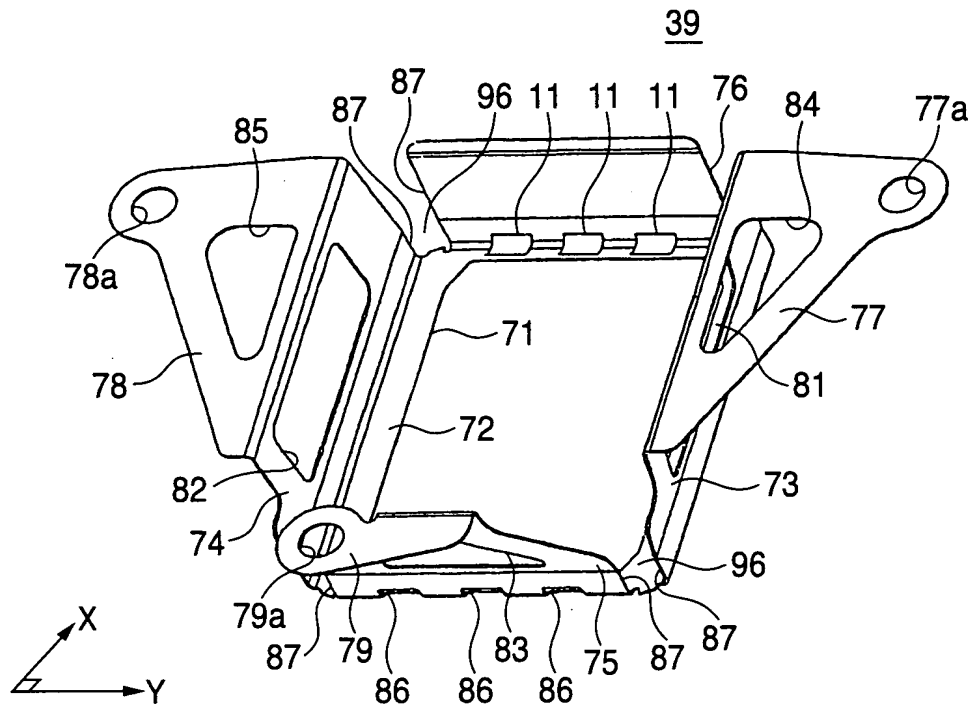
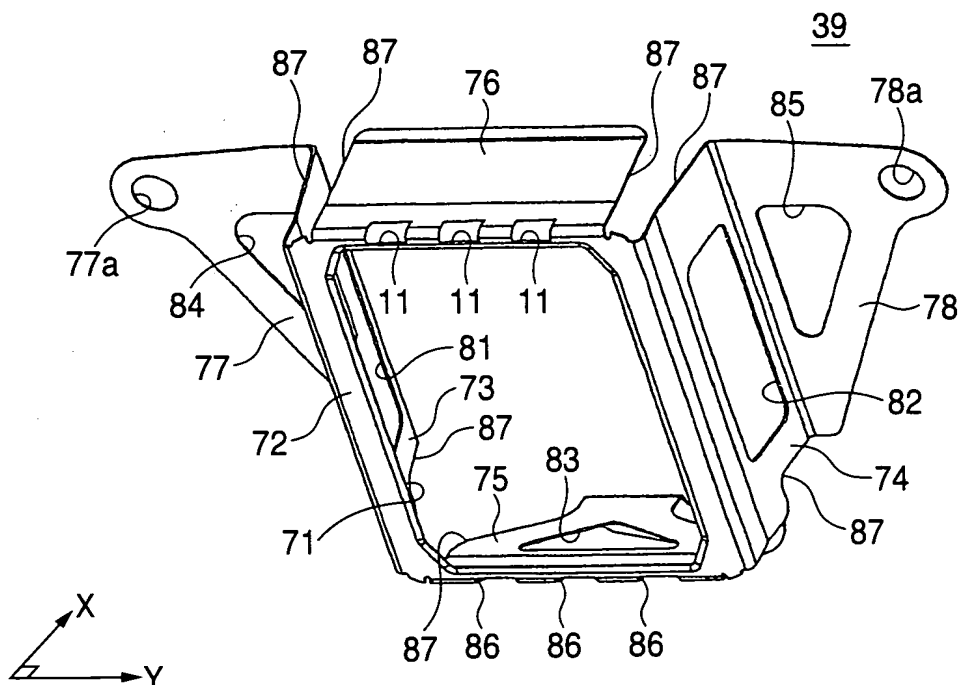
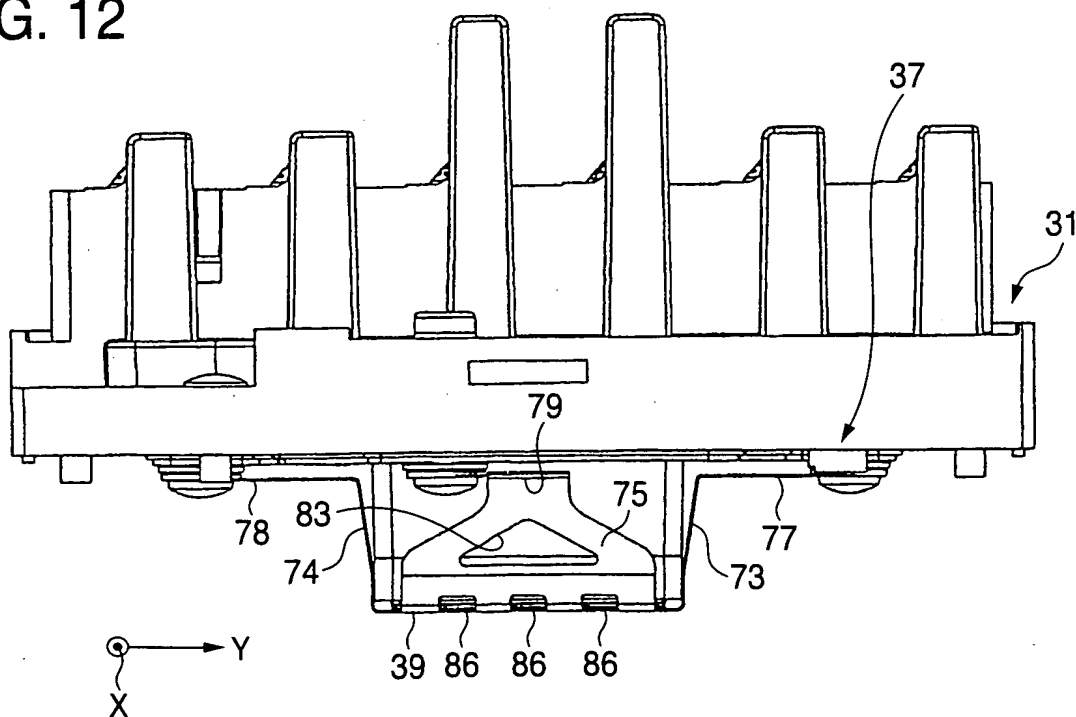
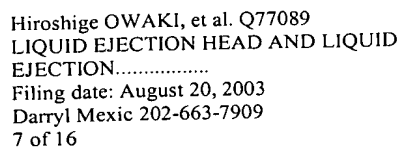


FIG. 10









This diagram shows the assembly from a different perspective, illustrating the movement of the upper housing 78. The upper housing 78 is shown in a position where it can move relative to the lower housing 77, as indicated by the curved arrow labeled R. The lower housing 77 contains various internal components, including the base plate 16, the support structure 15, and the actuator mechanism 17. The upper housing 78 has a top surface 72 and side walls 71, 73, 74, 75, 76, 77, 78. It also features a hinge or pivot point 39 and a locking mechanism 79. The assembly is mounted on a base 109.

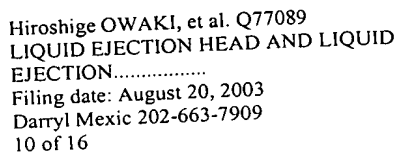


FIG. 1 is a cross-sectional view of a semiconductor device. It shows a substrate 12 with a top surface 39. A layer 17 is on the left, and a layer 61 is on the right. A horizontal layer 38 is on top of 12, with a section labeled S2. A structure 109 is on the bottom right.



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FIG. 18

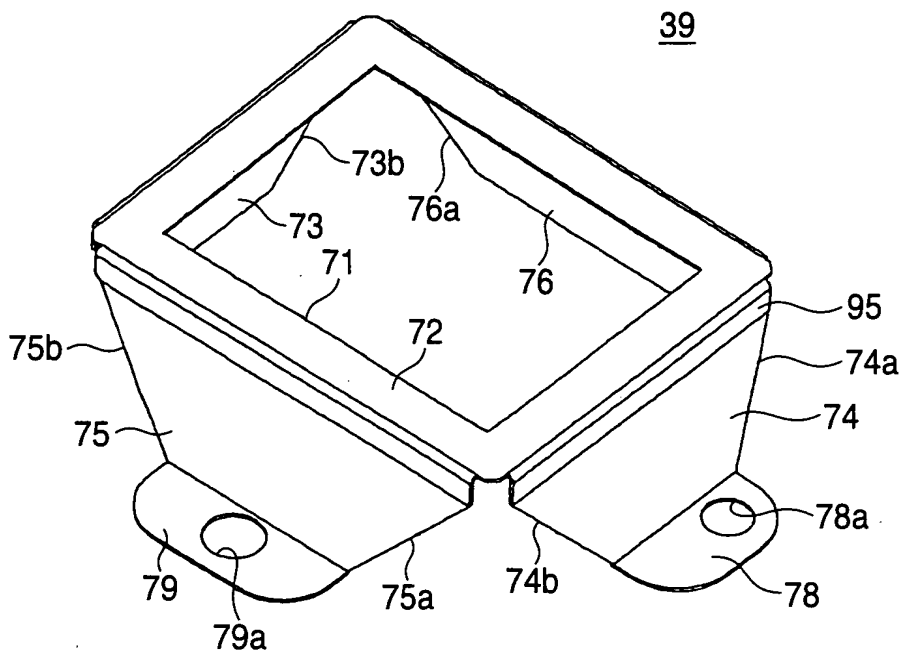
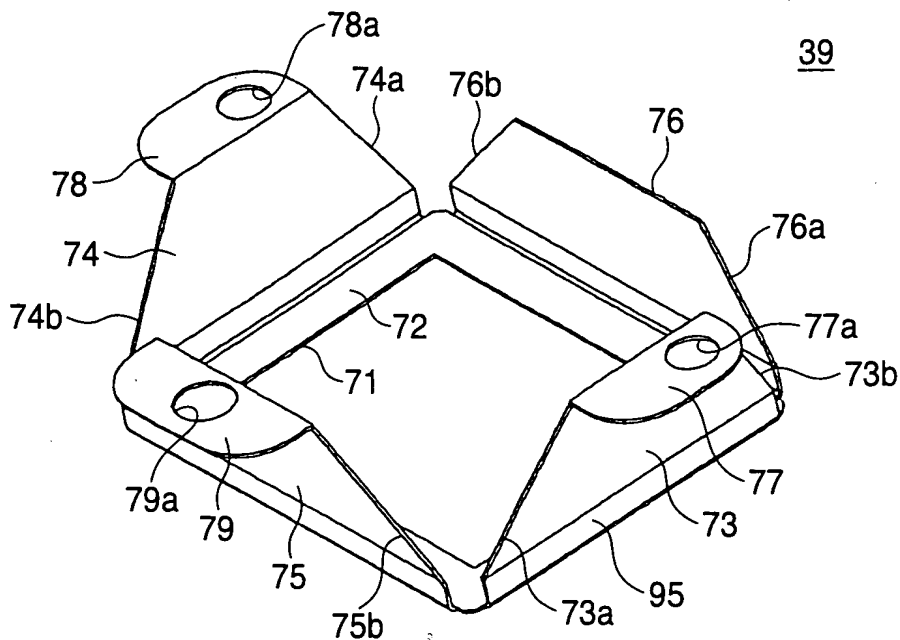


FIG. 19





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FIG. 20

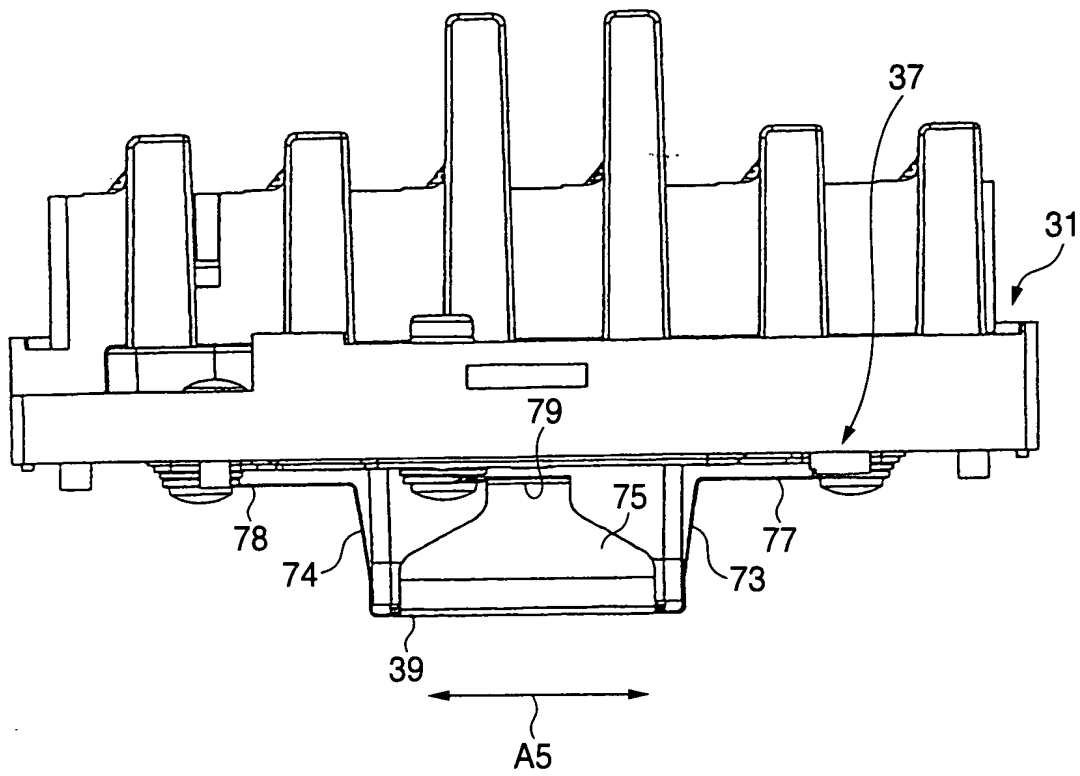




FIG. 21

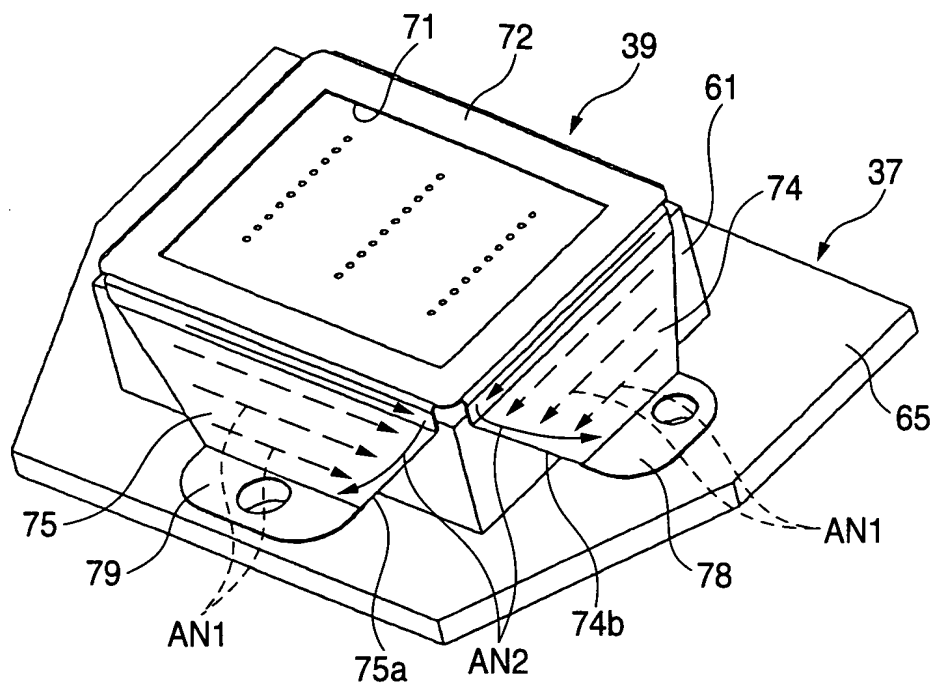
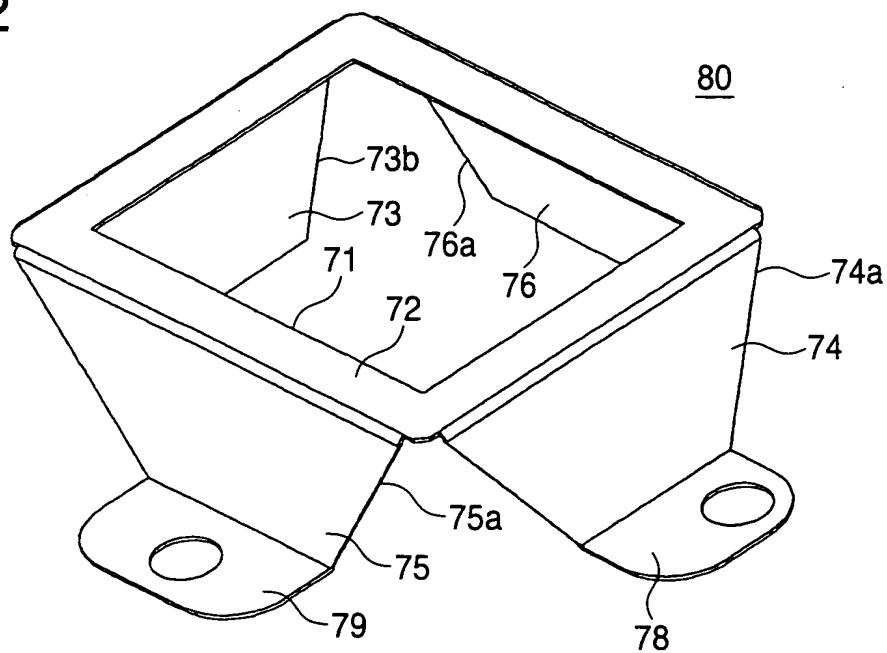


FIG. 22





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FIG. 23

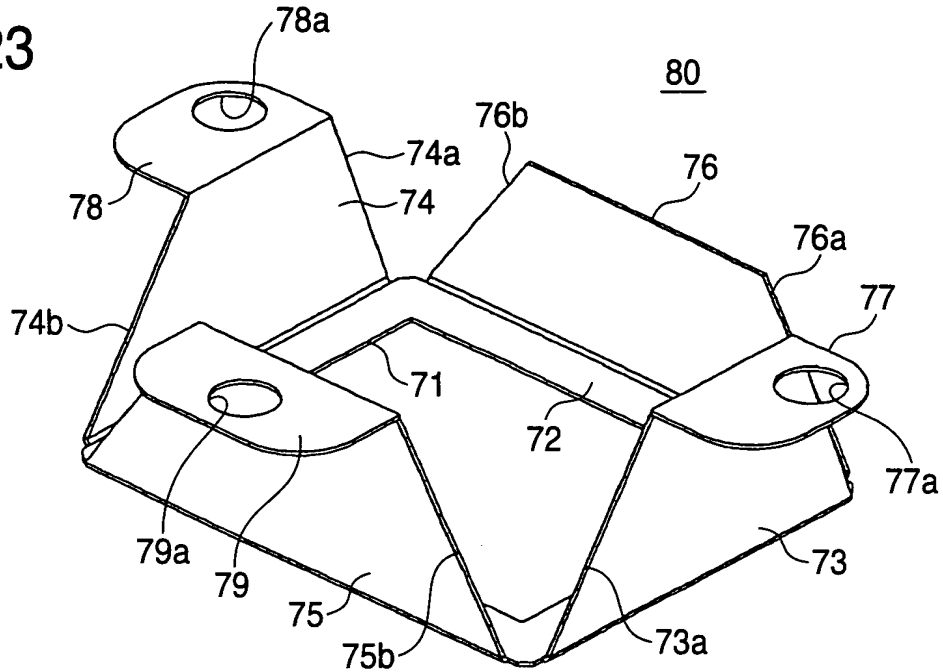
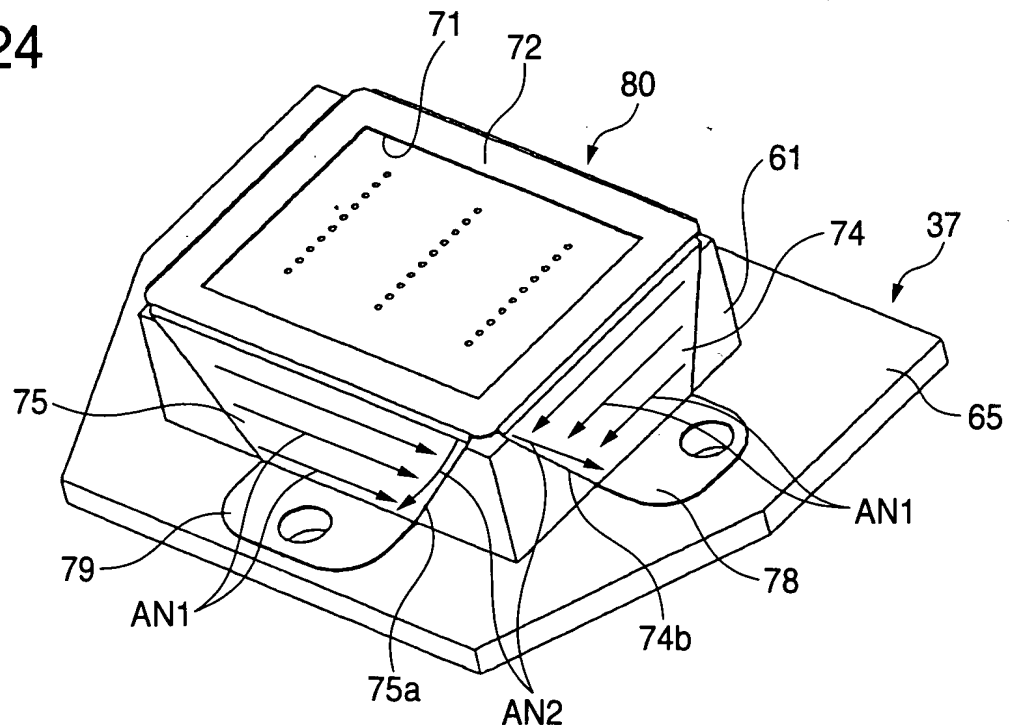


FIG. 24



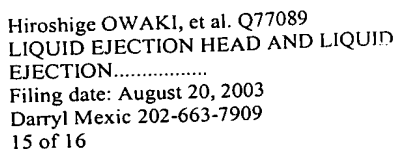
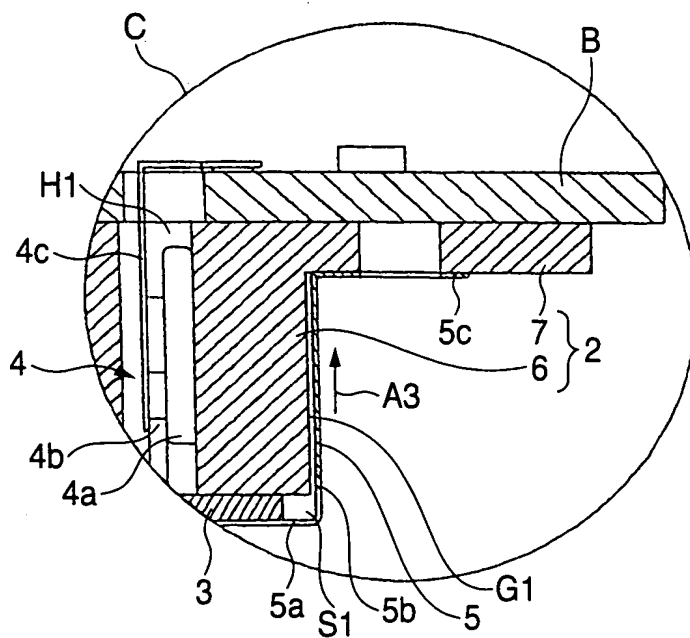


FIG. 25



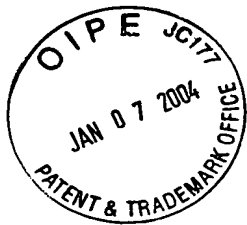


FIG. 27

